

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A processor loading apparatus comprising:
 - a board member;
 - a processor socket mounted on the board member;
 - a processor seated in the processor socket;
 - a frame member mounted on the board member;
 - a plurality of connector portions on the frame member; and
 - a curved resilient load member with a first end connected to one of the connector portions and a second end connected to another one of the connector portions, whereby the connection of the second end deforms the curved load member into a substantially parallel engagement with the processor and urges the processor into the processor socket.
2. (Original) The apparatus of claim 1 wherein the frame member surrounds the processor socket.
3. (Original) The apparatus of claim 1 further comprising:
 - a support member mounted on the board member adjacent to the frame member.
4. (Original) The apparatus of claim 1 wherein the first end of the resilient load member is pivotally connected to one of the connector portions and the second end is latched to another one of the connector portions.
5. (Original) The apparatus of claim 1 wherein the processor includes a thermal connection surface.
6. (Original) The apparatus of claim 5 wherein the resilient load member includes an opening whereby when the second end of the resilient load member is forcibly connected to its respective connector portion, the thermal connection surface is exposed in the opening.

7. (Currently Amended) A heat sink mounting apparatus comprising:
- a board member;
 - a support member mounted on the board member;
 - a processor socket mounted on the board member;
 - a processor seated in the processor socket;
 - a frame member mounted on the board member;
 - a plurality of connector members on the frame member;
 - a curved resilient load member with a first end connected to one of the connector members and a second end connected to another one of the connector members, whereby the connection of the second end deforms the curved load member into a substantially parallel engagement with the processor and urges the processor into the processor socket; and
 - a heat sink mounted on the frame and adjacent to the load member.
8. (Original) The apparatus of claim 7 wherein the frame member surrounds the processor socket.
9. (Original) The apparatus of claim 7 wherein the support member is mounted on an opposite side of the board from the frame member.
10. (Original) The apparatus of claim 7 wherein the first end of the resilient load member includes a pivotal connection and the second end includes a latched connection.
11. (Original) The apparatus of claim 7 wherein the processor includes a thermal connection surface.
12. (Original) The apparatus of claim 11 wherein the resilient load member includes an opening whereby, when the second end of the resilient load member is forcibly connected to its respective connector portion, the thermal connection surface is exposed in the opening.
13. (Original) The apparatus of claim 12 wherein the heat sink engages the thermal connection surface.

14. (Currently Amended) An information handling system comprising:
- a board member;
 - a support member mounted on the board member;
 - a processor socket mounted on the board member and coupled to a mass storage device and a system memory;
 - a processor seated in the processor socket;
 - a frame member mounted on the board member;
 - a plurality of connector members on the frame member;
 - a curved resilient load member with a first end connected to one of the connector members and a second end connected to another one of the connector members, whereby the connection of the second end deforms curved the load member into a substantially parallel engagement with the processor and urges the processor into the processor socket; and
 - a heat sink connected to the frame member adjacent to the load member.
15. (Original) The system of claim 14 wherein the frame member surrounds the processor socket.
16. (Original) The system of claim 14 wherein the support member is adjacent the frame member.
17. (Original) The system of claim 14 wherein the first end of the resilient load member includes a pivotal connection and the second end includes a latched connection.
18. (Original) The system of claim 14 wherein the processor includes a thermal connection surface.
19. (Original) The system of claim 18 wherein the resilient load member includes an opening whereby, when the second end of the resilient load member is forcibly connected to its respective connector member, the thermal connection surface is exposed in the opening.

20. (Original) The system of claim 19 wherein the heat sink engages the thermal connection surface.
21. (Currently Amended) A method for mating a processor to a processor socket and mounting a heat sink in an information handling system comprising:
- providing a board member;
 - mounting a support member on the board member;
 - mounting a processor socket on the board member;
 - coupling a mass storage device and a system memory to the processor socket;
 - providing a processor seated in the processor socket;
 - mounting a frame member on the board member;
 - providing a plurality of connector members on the frame member;
 - providing a curved resilient load member with a first end connected to one of the connector members and a second end connected to another one of the connector members, whereby the connection of the second end deforms the curved load member into a substantially parallel engagement with the processor and urges the processor into the processor socket; and
 - providing a heat sink connected to the frame member adjacent to the load member.